

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Jianhua Ju</td><td>01/25/2010</td></tr><tr><td>Xianjie Ning</td><td>01/25/2010</td></tr></tbody></table>		Name	Execution Date	Jianhua Ju	01/25/2010	Xianjie Ning	01/25/2010
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Jianhua Ju	01/25/2010						
Xianjie Ning	01/25/2010						
RECEIVING PARTY DATA							
Name:	Semiconductor Manufacturing International (Shanghai) Corp.						
Street Address:	18 Zhang Jiang Road, Pudong New Area						
City:	Shanghai						
State/Country:	CHINA						
Postal Code:	201203						
PROPERTY NUMBERS Total: 1							
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12708469</td></tr></tbody></table>		Property Type	Number	Application Number:	12708469		
Property Type	Number						
Application Number:	12708469						
CORRESPONDENCE DATA							
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Total Attachments: 2 source=88644_64assign#page1.tif source=88644_64assign#page2.tif							

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PATENT
REEL: 023965 FRAME: 0470

ASSIGNMENT

Insert Name(s) of Inventor(s) (1) Jianhua JU
(2) Xianjie NING

For good and valuable consideration, receipt of which is hereby acknowledged, the undersigned agrees to assign, hereby does assign, transfer and set over to:

(5) Insert Name of Assignee (5) Semiconductor Manufacturing International (Shanghai) Corporation

(6) Insert Address of Assignee (6) of: 18 Zhang Jiang Road, Pudong New Area, Shanghai, 201203 P.R. China (hereinafter designated as the Assignee) the entire worldwide right, title, interest, and patent applications and patents for every country, including divisions, reissues, continuations and all other extensions, rights and priorities in the invention known as and related to

(7) Insert Identification of Invention, such as Title, Case Number or Foreign Application Number (7) Title: RAPID THERMAL ANNEALING METHOD FOR A SEMICONDUCTOR DEVICE

Attorney Docket No. 88644.17, Serial No. 12/708,469 for which the undersigned has executed an application for patent in the United States of America

(8) Insert Date of Signing of Application (8) on January 25, 2010

- 1) The undersigned agrees to execute all papers necessary in connection with the application and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.
- 2) The undersigned agrees to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.
- 3) The undersigned agrees to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

- 4) The undersigned agrees to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.
- 5) The undersigned hereby authorizes and requests the Commissioner of Patents and the duly constituted authorities of foreign countries to issue any and all Letters Patents resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, its successors and assigns, as Assignee of the entire right, title and interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has not executed and will not execute any agreement in conflict herewith.
- 6) *The undersigned hereby grant(s)*

Song Zhu, Reg. No. 44,420

Cameron K. Kerrigan, Reg. No. 44,826; Mark Lupkowski, Reg. No. 49,010; Zhaoyang Li, Reg. No. 46,872; Bernard F. Rose, Reg. No. 42,112; Angie Augustus, Reg. No. 51,421; Jeff Talkington, Reg. No. 58,381; Ram Sabnis, Reg. No. 58,868.

the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date Jan. 25, 2010

Signature of Inventor: Jianhua Ju
Jianhua JU

Date 1/25/2010

Signature of Inventor: Xianjie Ning
Xianjie NING